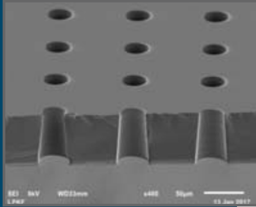
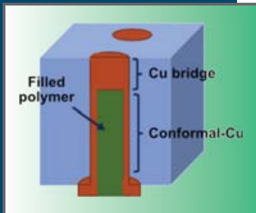
Advanced Packaging Update:

Market and Technology Trends

Vol. 2-0721





This issue of the Advanced Packaging Update presents new developments in integrated photonics. An updated analysis of the substrate capacity shortage is presented with a focus on build-up substrates for flip chip packages. New substrate developments, including high-density RDL interposers are highlighted. TechSearch International's annual survey on substrate design rules is presented with special coverage of suppliers of laminate flip chip BGA and CSP substrates worldwide. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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